# 2SC3936

# Silicon NPN epitaxial planar type

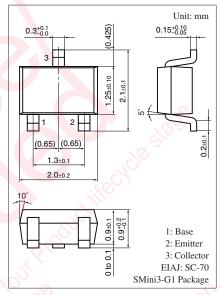
### For high-frequency amplification

### ■ Features

- Optimum for RF amplification, oscillation, mixing, and IF of FM/AM radios
- S-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

## ■ Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	$V_{CBO}$	30	V	
Collector-emitter voltage (Base open)	$V_{CEO}$	20	V	
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	5	V	
Collector current	$I_{C}$	30	mA	
Collector power dissipation	$P_{C}$	150	mW	
Junction temperature	T <sub>j</sub>	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	



Marking Symbol: K

# ■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

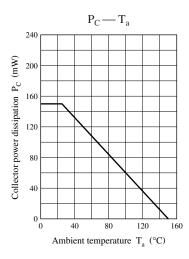
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_C = 10 \mu\text{A}, I_E = 0$	30			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 2 \text{ mA}, I_B = 0$	20			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = 10 \mu\text{A},  I_C = 0$	5			V
Forward current transfer ratio *	$h_{FE}$	$V_{CE} = 10 \text{ V}, I_{C} = 1 \text{ mA}$	70		250	_
Transition frequency	$f_T$	$V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}, f = 200 \text{ MHz}$	150	230		MHz
Reverse transfer capacitance	C <sub>re</sub>	$V_{CB} = 10 \text{ V}, I_{E} = -1 \text{ mA}, f = 10.7 \text{ MHz}$		1.3		pF
(Common emitter)		it is all.				

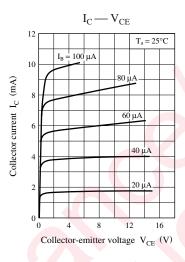
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

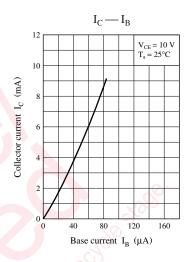
### 2. \*: Rank classification

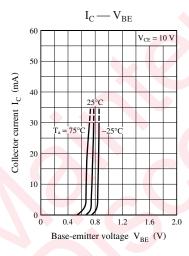
Rank	В	C 2
h <sub>FE</sub>	70 to 160	110 to 250

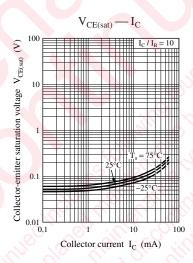
# **Panasonic**

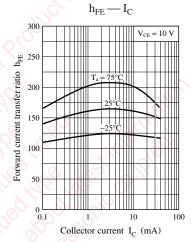


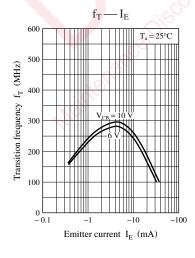


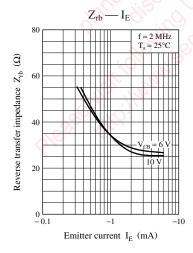


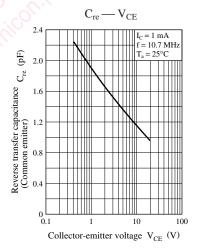




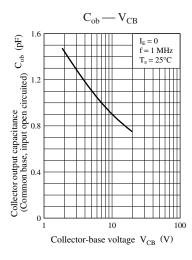


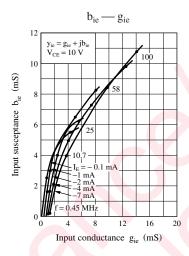


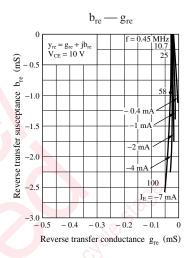


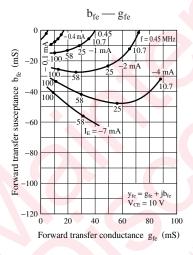


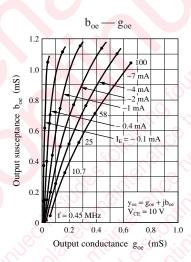
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